

U.S. Patent Application Serial No. 10/531,075
Response filed October 28, 2008
Reply to OA dated May 28, 2008

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (currently amended): A heat shielding material for an agricultural and horticultural facility, comprising:

a heat shield layer comprising a substrate resin and a heat shield filler in the form of particles kneaded in said substrate resin, said heat shield layer being in the form of a single film or board, wherein said substrate resin in said heat shield layer is at least one selected from polyethylene resin, polyvinyl chloride resin and polypropylene resin, said heat shield filler in said heat shield layer is at least one selected from lanthanum hexaboride and antimony-doped tin oxide, and the content of said heat shield filler in said heat shield layer is in the range of 0.01 to 1 g/m² for the lanthanum hexaboride and in the range of from about 1.0 to 50 g/m² for the antimony-doped tin oxide.

Claim 2 (previously presented): A heat shielding material for an agricultural and horticultural facility according to claim 1 or 5, having a visible light transmittance in the range of 30 to 90%, and a solar radiation transmittance in the range of 10 to 80%, wherein said visible light transmittance is set to be larger by 10% or above than said solar radiation transmittance.

Claims 3-4 (canceled).

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Claim 5 (currently amended): A heat shielding material for an agricultural and horticultural facility, comprising a heat shield layer comprising a substrate resin and a heat shield filler in the form of particles kneaded in said substrate resin, said heat shield layer being in the form of a single film or board and in a form in which said heat shield layer has been laminated on the surface of a single film or board matrix material, or has been sandwiched between two of said matrix ~~material~~ materials, wherein said substrate resin in said heat shield layer is at least one selected from polyethylene resin, polyvinyl chloride resin and polypropylene resin, said heat shield filler in said heat shield layer is ~~at least one selected from lanthanum hexaboride and antimony-doped tin oxide~~, and the content of said heat shield filler in said heat shield layer is in the range of 0.01 to 1 g/m² ~~for the lanthanum hexaboride and in the range of from about 1.0 to 50 g/m² for the antimony-doped tin oxide.~~